Kingbright

3.5x2.8mm SURFACE MOUNT LED LAMP

Part Number: KA-3528YS Yellow

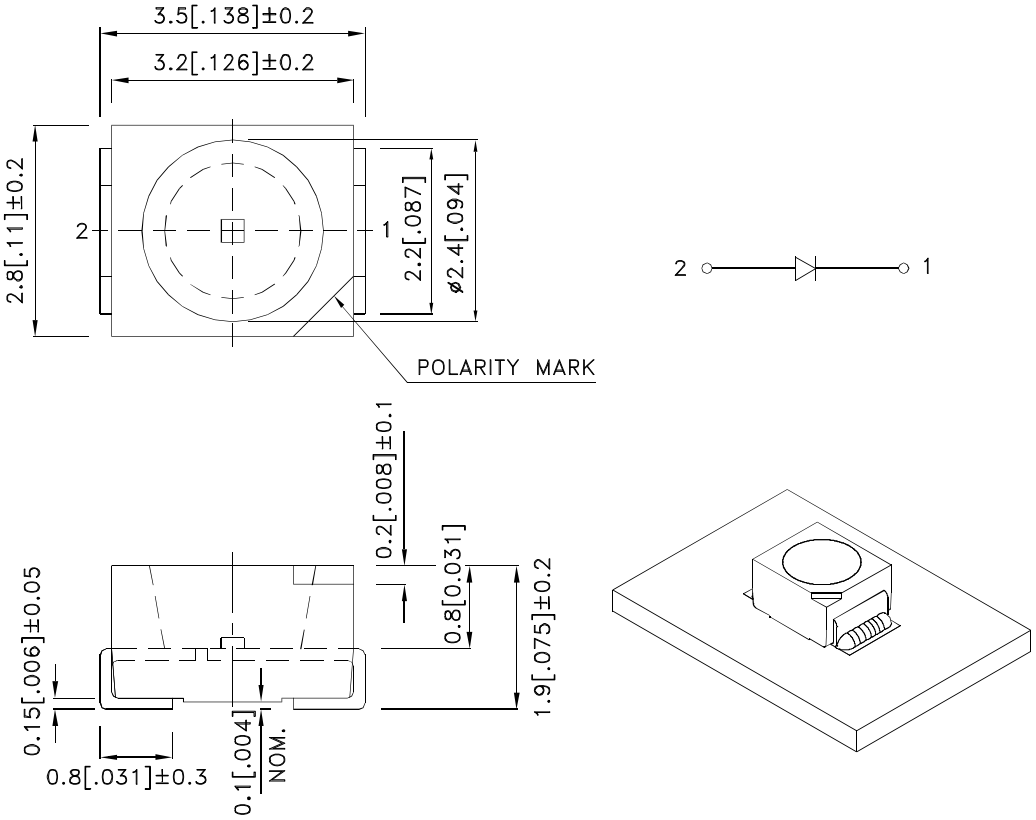
Features

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package : 1500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions

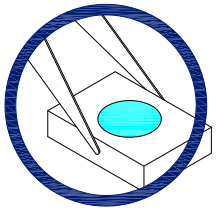


Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4.The device has a single mounting surface. The device must be mounted according to the specifications.

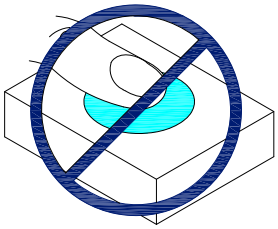
Handling Precautions

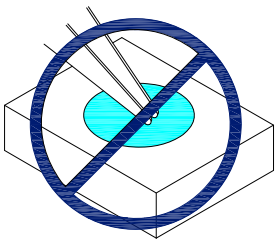
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

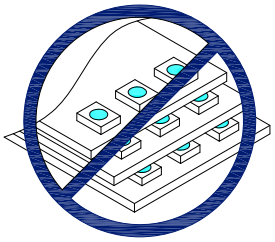


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

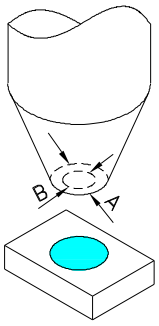




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KA-3528YS	Yellow (GaAsP/GaP)	Water Clear	10	20	120°

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

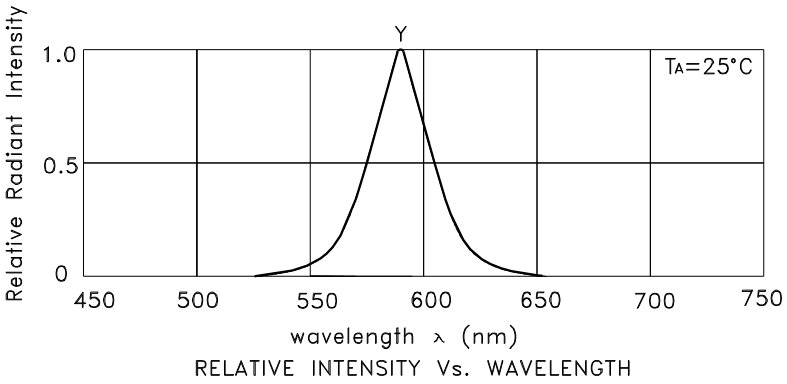
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	I_F=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	I_F=20mA
C	Capacitance	Yellow	20		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	Yellow	2.1	2.5	V	I_F=20mA
I_R	Reverse Current	Yellow		10	uA	V_R=5V

Notes:
1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

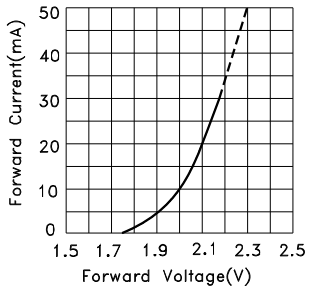
Parameter	Yellow	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

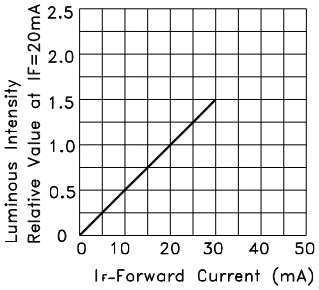


RELATIVE INTENSITY Vs. WAVELENGTH

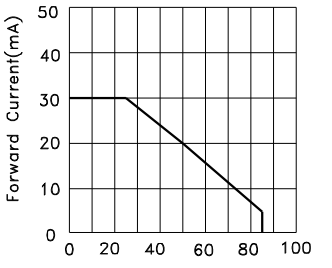
Yellow **KA-3528YS**



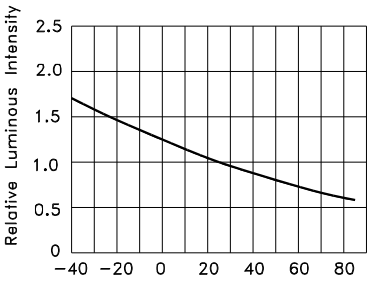
FORWARD CURRENT Vs.
FORWARD VOLTAGE



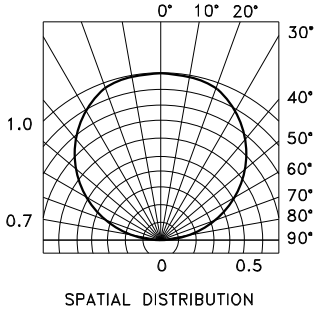
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

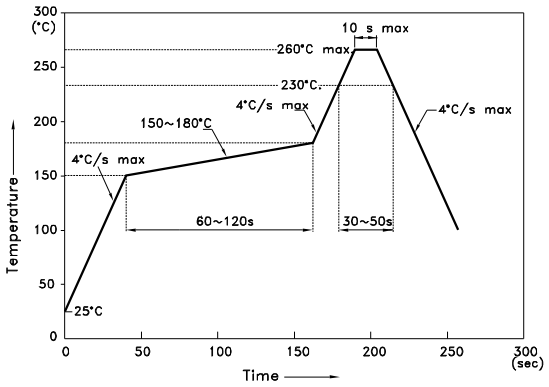


SPATIAL DISTRIBUTION

KA-3528YS

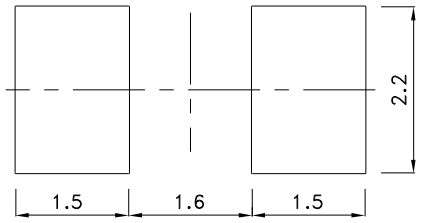
Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

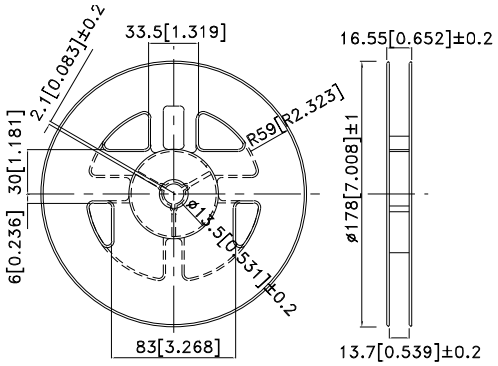


NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

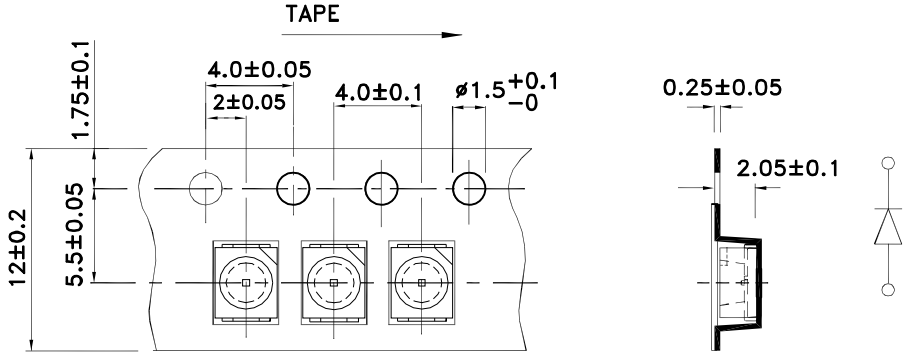
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS **KA-3528YS**